

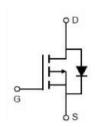
# MJ P-Channel Enhancement Mode Power MOSFET

### Description

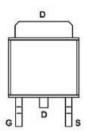
The MJ60P14AK uses advanced trench technology and design to provide excellent  $R_{\text{DS(ON)}}$  with low gate charge. This device is well suited for use as a load switch or in PWM applications.

#### General Features

- $ightharpoonup V_{DS} = -60 \text{V}, I_D = -14 \text{A}$   $R_{DS(ON)} < 75 \text{m}\Omega$  @ V<sub>GS</sub>=-10 V  $R_{DS(ON)} < 96 \text{m}\Omega$  @ V<sub>GS</sub>=-4.5 V
- ♦ High density cell design for ultra low Rdson
- ◆ Fully characterized avalanche voltage and current
- ◆ Excellent package for good heat dissipation





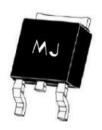


Application

Load switch

PWM application

Marking and pin assignment



TO-252-2L top view

### 100% UIS TESTED! 100% ΔVds TESTED!

# Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ60P14AK	MJ60P14AK	TO-252-2L	2	<u>=</u>	9

### Absolute Maximum Ratings (Tc =25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	-14	Α
Pulsed Drain Current	Ідм	-56	А
Maximum Power Dissipation	Po	50	W
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 175	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rөjc	3.0	°C/W
Thermal Redictation, surface to Gues	1 (030	0.0	C/ VV





# Electrical Characteristics (Tc =25°Cunless otherwise noted)

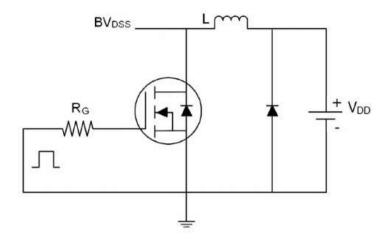
Drain-Source Breakdown Voltage   BVpss   Vos=00V lo=-250µA   -60   -   -   V Zero Gate Voltage Drain Current   loss   Vos=-60V,Vos=0V   -   -   -1   µA Gate-Body Leakage Current   loss   Vos=220V,Vos=0V   -   -   -1   100   nA On Characteristics (Nike 3)	Parameter	Symbol	Condition	Min	Тур	Max	Unit
Zero Gate Voltage Drain Current   1050	Off Characteristics	'	1				
Gate-Body Leakage Current   Ioss   Vos=±20V,Vos=0V   -   ±100   nA	Drain-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-60	-	_	V
On Characteristics (Notes 1)	Zero Gate Voltage Drain Current	loss	V <sub>DS</sub> =-60V,V <sub>GS</sub> =0V	-	-	-1	μΑ
Vos   Vos	Gate-Body Leakage Current	lgss	V <sub>DS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
Drain-Source On-State Resistance   Rosyonal   Vos=-10V, Io=-14A   - 63   75   mC	On Characteristics (Note 3)						
Prain-Source On-State Resistance   Rosicon   Vos=-4.5V, Io=-10A   - 74   96   mC	Gate Threshold Voltage	VGS(th)	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-1.0	-1.5	-2.0	V
Vos=-4.5V, Io=-10A	Desire Courses On Otata Desiretana	D.	V <sub>GS</sub> =-10V, I <sub>D</sub> =-14A	_	63	75	mΩ
Dynamic Characteristics   Notate 4	Drain-Source On-State Resistance	KDS(ON)	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A	-	74	96	mΩ
Description   Cost   Cost   Vos=-30V,Vos=0V   F=1.0MHz   - 85   - PF	Forward Transconductance	grs	V <sub>DS</sub> =-5V,I <sub>D</sub> =-14A	-	10	-	S
Output Capacitance   Coss   Vos=-30V,Vos=0V   F=1.0MHz   - 85   - PF	Dynamic Characteristics (Note 4)	'	1				
Feature   Fea	Input Capacitance	Clss		-	930	-	PF
Switching Characteristics (Note 4)	Output Capacitance	Coss		-	85	-	PF
Turn-on Delay Time         tota(on)         -         8         -         nS           Turn-on Rise Time         total Calculus         -         4         -         nS           Turn-Off Delay Time         total Calculus         -         32         -         nS           Turn-Off Fall Time         total Calculus         -         -         -         -         -         -         nS           Total Gate Charge         Qg         Vbs=-30V, lb=-14A         -         -         25         -         nC           Gate-Source Charge         Qgd         Vbs=-30V, lb=-14A         -         3         -         nC           Gate-Drain Charge         Qgd         Vss=-10V         -         -         -         nC           Drain-Source Diode Characteristics         Vsp         Vgs=0V, ls=-14A         -	Reverse Transfer Capacitance	Crss	•	-	35	-	PF
Turn-on Rise Time         tr         V <sub>DD=-30V, RL=2Ω</sub> V <sub>SS=-10V,RG=3Ω</sub> - 4 - nS           Turn-Off Delay Time         t <sub>d(off)</sub> - 32 - nS           Turn-Off Fall Time         - 7 - nS           Total Gate Charge         Q <sub>g</sub> - 25 - nC           Gate-Source Charge         Q <sub>gs</sub> V <sub>DS=-30V,ID=-14A</sub> V <sub>GS=-10V</sub> - 3 - nC           Gate-Drain Charge         Q <sub>gd</sub> - 7 - nC           Drain-Source Diode Characteristics         V <sub>SD</sub> V <sub>GS=0V,Is=-14A</sub>	Switching Characteristics (Note 4)						
Turn-Off Delay Time   td(off)   V <sub>DS</sub> =-30V, R <sub>I</sub> =2Ω   V <sub>SS</sub> =-10V;R <sub>G</sub> =3Ω   - 32   - nS	Turn-on Delay Time	t <sub>d(on)</sub>		-	8	_	nS
Turn-Off Delay Time         t <sub>d(off)</sub> V <sub>GS</sub> =-10V,R <sub>G</sub> =3Ω         -         32         -         nS           Turn-Off Fall Time         tr         -         7         -         nS           Total Gate Charge         Qg         -         25         -         nC           Gate-Source Charge         Qgs         V <sub>DS</sub> =-30V,I <sub>D</sub> =-14A V <sub>GS</sub> =-10V         -         3         -         nC           Gate-Drain Charge         Qgd         -         7         -         nC           Drain-Source Diode Characteristics           Diode Forward Voltage (Note 3)         V <sub>SD</sub> V <sub>GS</sub> =0V,I <sub>S</sub> =-14A         -         -         -1.2         V           Diode Forward Current (Note 2)         Is         -         -         -         -14         A           Reverse Recovery Time         tr         T <sub>J</sub> =25°C, I <sub>F</sub> =-14A di/dt=-100A/µs (Note 3)         -         -         25         -         nS	Turn-on Rise Time	tr	Vpp=-30V R1=20	-	4	-	nS
Total Gate Charge   Qg	Turn-Off Delay Time	t <sub>d(off)</sub>		-	32	-	nS
Gate-Source Charge   Qgs   VDS=-30V, ID=-14A   - 3   - ID	Turn-Off Fall Time	tr		-	7	-	nS
Gate-Source Charge   Ggs   Ves=-10V   -   3	Total Gate Charge	Qg		-	25	_	nC
Drain-Source Diode Characteristics           Diode Forward Voltage (Note 3)         VSD         Ves=0V,Is=-14A         -         -         -1.2         V           Diode Forward Current (Note 2)         Is         -         -         -14         A           Reverse Recovery Time         trr         TJ=25°C, IF=-14A di/dt=-100A/µs (Note 3)         -         25         -         nS	Gate-Source Charge	Qgs		-	3	-	nC
Diode Forward Voltage (Note 3)         VSD         Vos=0V,Is=-14A         -         -         -1.2         V           Diode Forward Current (Note 2)         Is         -         -         -14         A           Reverse Recovery Time         trr         TJ=25°C, IF=-14A di/dt=-100A/µs (Note 3)         -         25         -         nS	Gate-Drain Charge	Qgd		-	7	-	nC
Diode Forward Current (Note 2)  Is 14 A  Reverse Recovery Time  trr  TJ=25°C, IF=-14A di/dt=-100A/µs (Note 3)	Drain-Source Diode Characteristics		I			I	<u> </u>
Reverse Recovery Time	Diode Forward Voltage (Note 3)	VsD	V <sub>GS</sub> =0V,I <sub>S</sub> =-14A	-	-	-1.2	V
di/dt=-100A/µs (Note 3)	Diode Forward Current (Note 2)	Is		-	-	-14	А
di/dt=-100A/µs <sup>(Note 3)</sup>	Reverse Recovery Time	trr	T = 25°C   E = 14A	-	25	_	nS
	Reverse Recovery Charge	Qrr	di/dt=-100A/µs (Note 3)	_	31	_	nC

# Notes:

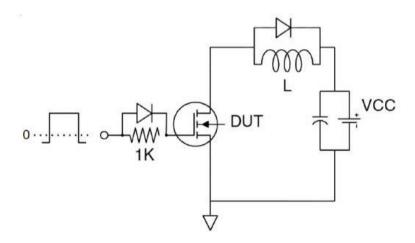
- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3 Pulse Test; Pulse Width  $\leq 300 \mu s$ , Duty Cycle  $\leq 2\%$ .
- 4 Guaranteed by design, not subject to production



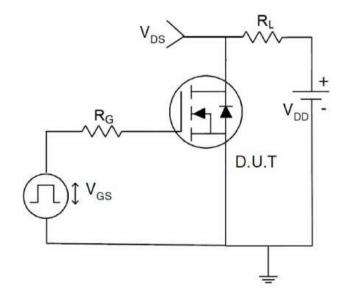
# Test circuit



Eas test Circuit



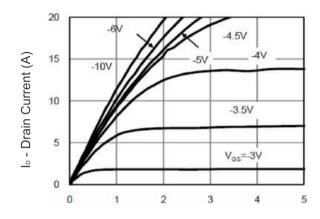
Gate charge test Circuit



Switch Time Test Circuit

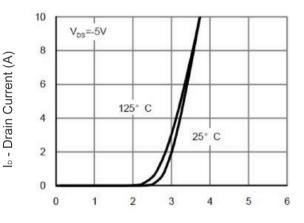


# Typical Electrical and Thermal Characteristics (Curves)



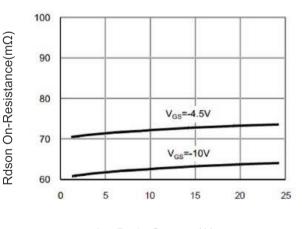
Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



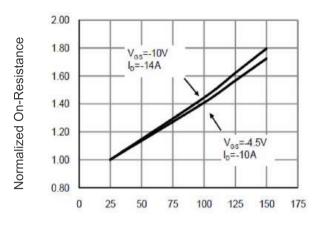
Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



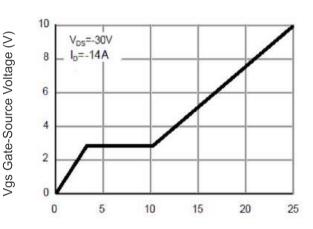
-l₀ - Drain Current (A)

Figure 3 Rdson- Drain Current



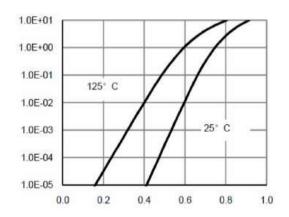
T<sub>J</sub> -Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)

Figure 5 Gate Charge



-Vsd Source-Drain Voltage (V)

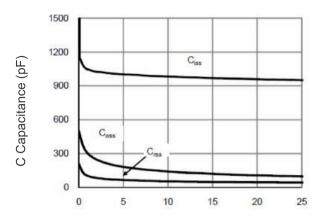
Figure 6 Source- Drain Diode Forward

Is - Reverse Drain Current (A)

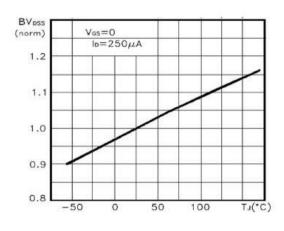


Ib - Drain Current (A)

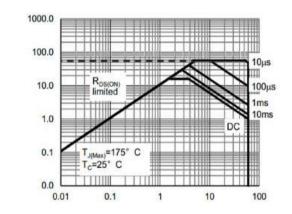




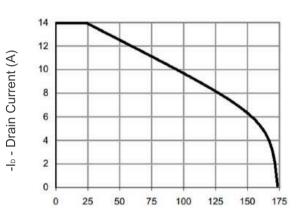
-Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



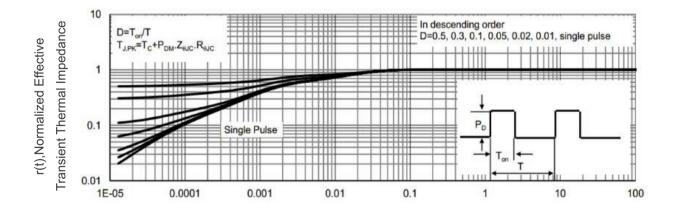
TJ -Junction Temperature(°C)
Figure 9 BVpss vs Junction Temperature



-Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



T<sub>J</sub> -Junction Temperature(°C)
Figure 10 I<sub>D</sub> Current De-rating



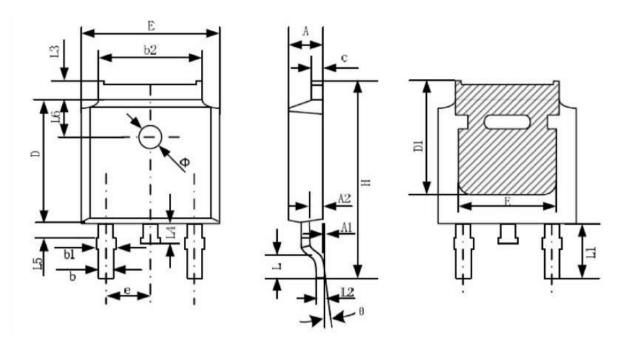
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance





# TO-252-2L Package Information



Complete	Dimensions	In Millimeters	Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
A	2.20	2.38	0.087	0.094
A1	0.00	0.10	0.000	0.004
A2	0.90	1.10	0.035	0.043
b	0.72	0.85	0.028	0.033
b1	0.72	0.90	0.028	0.035
b2	5.13	5.46	0.202	0.215
с	0.47	0.60	0.019	0.024
D	6.00	6.20	0.236	0.244
D1	5.25	=	0,207	
E	6.50	6.70	0.256	0.264
E1	4.70	-	0.185	-
e	2.19	2.39	0.086	0.094
Н	9.80	10.40	0.386	0.409
L	1.40	1,70	0.055	0.067
L1	2.90	REF	0.114 REF	
L2	0.508 BSC		0.020 BSC	
L3	0.90	1.25	0.035	0.049
L4	0.60	1.00	0.024	0.039
L5	0.15	0.75	0.006	0.030
L6	1.80	REF	0.071 REF	
Φ	1.20	1.40	0.047	0.055
θ	0°	8°	0°	8°





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